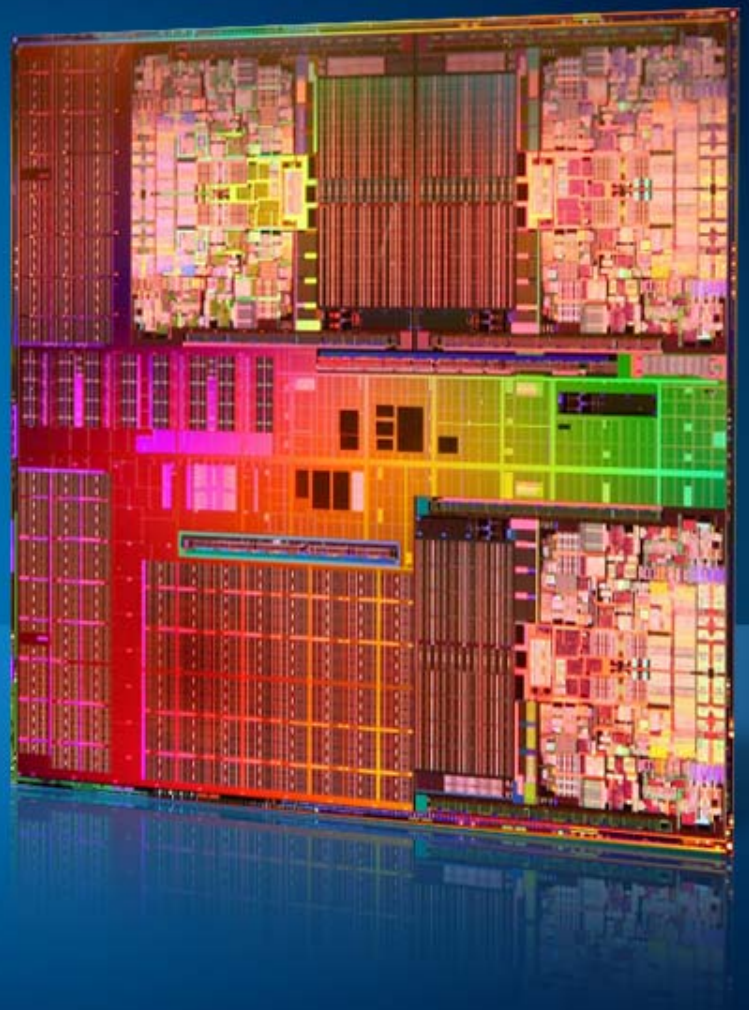
Introducing the
Intel® Xeon® Processor 7400 Series



Tom Kilroy
Vice President & General Manager
Digital Enterprise Group

September 15th, 2008

Intel® Xeon® 7400 Series

- 45nm Hi-k manufacturing process
- ~50%* more performance and 10% lower power **
- Critical new virtualization features
- Leading OEM's delivering innovative products

**Compared to the Intel® Xeon® 7300 series

* Up to approximately 50% performance result based on TPC*-E improvement compared to prior generation. For details visit http://www.intel.com/performance/server/xeon_mp/summary.htm

High-End Enterprise Trends

Data Demanding Performance

Corporate Data Growing 50X in 3 Years (source IDC)

Unstructured Data Proliferation

Flexible Resource Utilization

Virtualization the engine for better utilization

Shift to Virtualization 2.0

Standardization

TCO is the primary motivator

Xeon® Cost and Flexibility Advantages

Energy Efficiency

Power and Cooling growing to >50% of OpEx

Low Voltage, Energy Efficient designs

Focusing on "*what matters*" to IT

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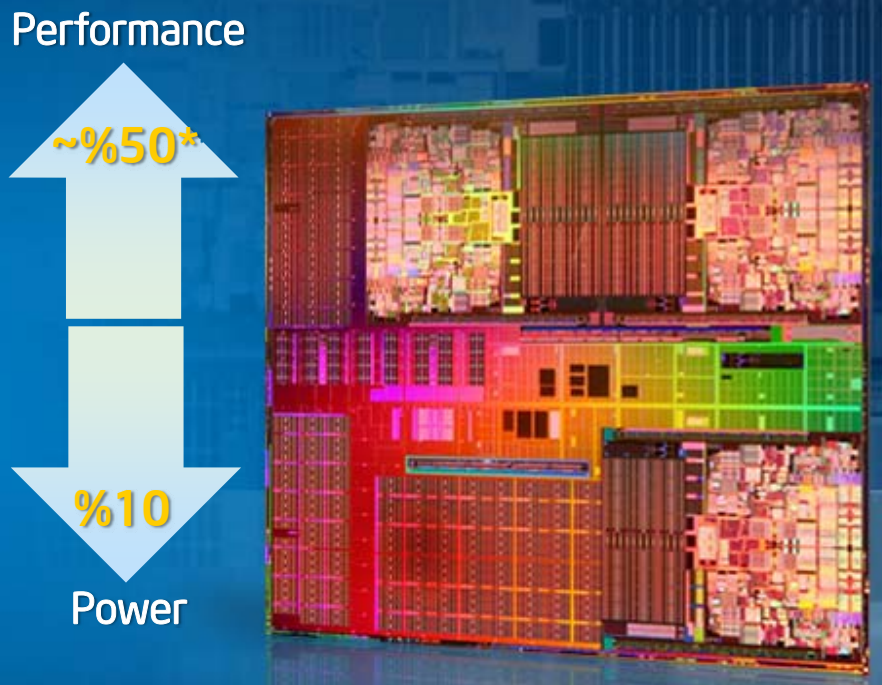
Intel® Xeon® 7400 Series

Technology Advantages

- 45nm Hi-K process
- 6-cores
- 16MB Shared L3 Cache
- Intel® VT FlexMigration
- LV Options at 50W
- Socket Compatible with Intel® 7300 platform

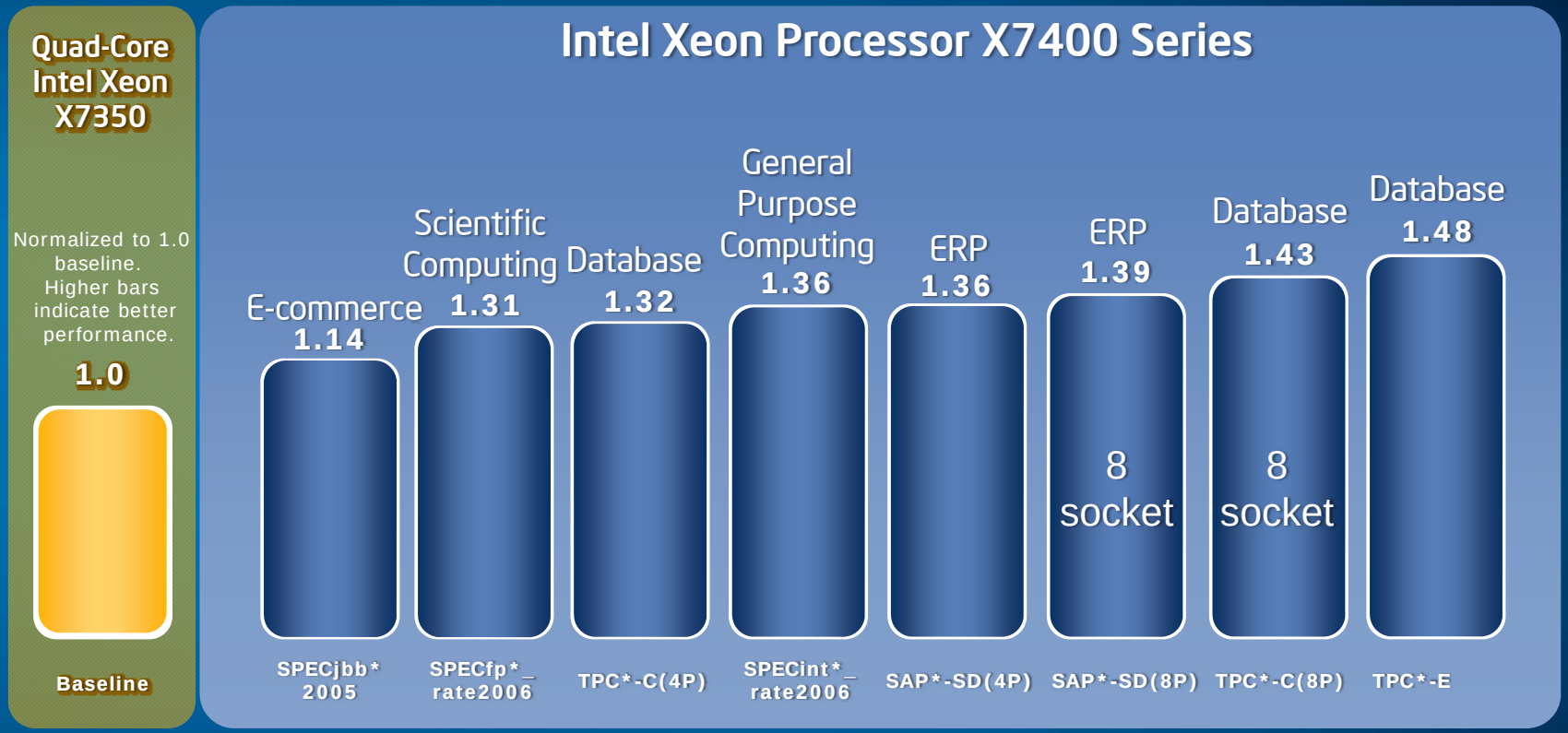


Extending MP Leadership

* Up to approximately 50% performance result based on TPC*-E improvement compared to prior generation.
For details visit http://www.intel.com/performance/server/xeon_mp/summary.htm

Intel® Xeon® 7400 Boosts Performance

Comparison to Current Generation Quad-core Intel® Xeon® 7300 Series



+ Source: Submitted, published, or Intel internally measured results, 15 August 2008. See backup slides for details.
X7350 published with 128 GB of memory and X7460 was published with 256 GB memory.

Enterprise Performance Records

8S TPC Benchmark* C-DB2 1,200,632 tpmC
First 1M+ TPC-C database result for x86

8S SAP*-SD 2 Tier
9200 Users

4S TPC Benchmark* C
684,508 tpmc

4S SAP-SD 2 Tier
5155 Users

TPC Benchmark* E
729 tpsE

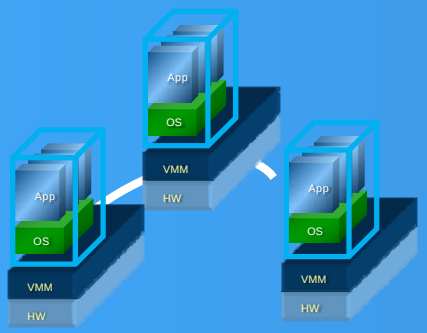
SPECjbb*2008
531,669 bops

VMware*Vmmark
18.49 Score

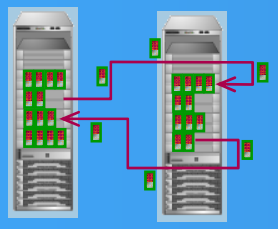
SPECint*_rate2006
291 peak score

*Other names and brands may be claimed as the property of others

Virtualization 2.0



Resource Pools



VM Migration over the network

Flexible Workload Management

Investment protection, across all segments

Enabled with Intel® VT FlexMigration

I/O tuned for Virtualization

Network and Storage Virtualization

Intel leadership with new innovations

HW-SW Compatibility

Broad portfolio of investment and collaboration

Enable the ecosystem with new platform capabilities

Virtualization Platform of Choice

ESX v3.5.0

VMware* VMmark* 4S Score

#1 18.49 at 14 Tiles

Windows Server® 2008

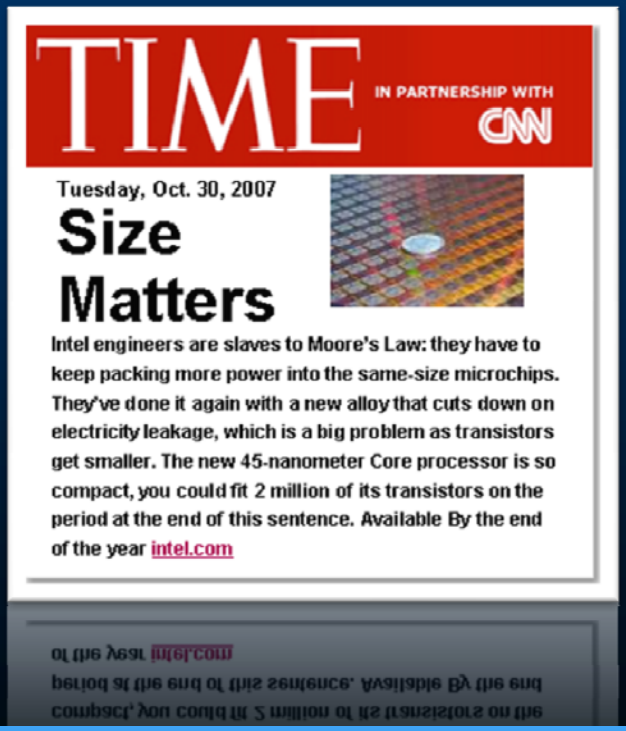
Hyper-V

VIRTUALIZATION PERFORMANCE Vs. Previous Gen Xeon 7300

40%

45nm Energy Efficiency Advantages

One of Time* Magazine's "Best Inventions" of the Year



TIME IN PARTNERSHIP WITH CNN

Tuesday, Oct. 30, 2007

Size Matters

Intel engineers are slaves to Moore's Law: they have to keep packing more power into the same-size microchips. They've done it again with a new alloy that cuts down on electricity leakage, which is a big problem as transistors get smaller. The new 45-nanometer Core processor is so compact, you could fit 2 million of its transistors on the period at the end of this sentence. Available By the end of the year intel.com

Intel® Xeon® 7400 Processor

- Over 50% better performance/watt*
- 10% less system power vs. 7300*
- 3 LV Processor Options

Lowest watts per core of any MP platform

* Compared to previous Generation Intel Xeon 7300

Source: http://www.time.com/time/specials/2007/article/0,28804,1677329_1678130_1678116,00.html

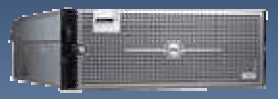
Innovative Platforms

4 Socket

ProLiant DL580 G5

ProLiant BL680c G5

System x3850 M2



UNISYS ES7000 Model 7600R

Sun microsystems SunFire x4450

Sun Blade x6450

SUPERMICRO SuperServer 8045C-3RB

Up to 16 Socket

IBM System x3950 M2

Unisys ES7000 Model 7600R

NEC Express 5800 Scalable Server

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Introducing End-User Panel

Diane Bryant *MODERATOR*
Intel Vice President & Chief Information Officer

Bohen Chen
VP Yahoo Database

Campbell Webb
VP Oracle Collaboration Suite IT

John Bosco
Principal Engineer

Richard Buckingham
VP of Technical Operations